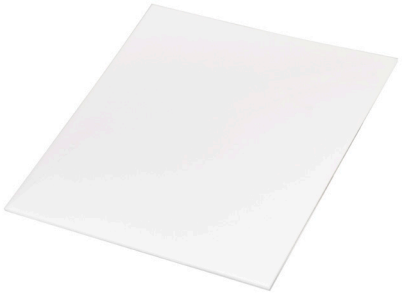
CUI DEVICES

SERIES: AF500 | **DESCRIPTION:** THERMAL PAD

FEATURES

- 3.0 W/m*K thermal conductivity
- naturally tacky
- silicone free
- electrical isolation
- sizes to match CUI Devices peltier footprints



RoHS

SPECIFICATIONS

parameter	test method/conditions/description	min	typ	max	units
material	non-silicone elastomer				
color	white				
thickness	ASTM D374		0.5		mm
specific gravity	ASTM D792		2.9		g/cc
hardness	ASTM D2240	65		90	shore OO
tensile strength	ASTM D412		30		psi
operating temperature		-40		130	°C
dielectric breakdown voltage	ASTM D149	200			Vac/mil
dielectric constant (1 MHz)	ASTM D150		8.0		
volume resistivity	ASTM D257		10^{13}		Ω*cm
thermal conductivity	ASTM D5470		3.0		W/m*K
thermal resistance	1 mm, 40 psi; ASTM D5470		0.6		°C*in²/W
compression ratio	1 mm, 40 psi		35		%
flammability rating	UL94V-0				
RoHS	yes				

PART NUMBER KEY

AF500 - XXXX 05

Base Number

Footprint Size (mm):

10x10 = 1010	15x15 = 1515
15x30 = 1530	20x20 = 2020
20x40 = 2040	26.25x50 = 2650
30x12 = 3012	30x30 = 3030
31.25x30 = 3130	40x40 = 4040
41.25x45 = 4145	50x50 = 5050
70x70 = 7070	

REVISION HISTORY

rev.	description	date
1.0	initial release	11/15/2018
1.01	brand update	03/23/2020
1.02	modified material	04/09/2021

The revision history provided is for informational purposes only and is believed to be accurate.